Amendments to the Claims

Please cancel Claims 4 and 14 and rewrite Claims 9-12 as follows:

1. (Previously Presented) A waveguide for a microwave device, comprising:

a frame housing a high-frequency circuit therein, the frame comprising a main casing housing a first circuit board and a sub-casing housing a second circuit board; and

a lid attached to a sidewall of the frame,

wherein the main casing has a cut-out formed in the sidewall to which the lid is attached, the sub-casing arranged inside the main casing has a sidewall which is exposed at the cut-out, both the main casing and the sub-casing have waveguide grooves formed in the respective sidewalls, the waveguide grooves extend along a mating surface between the frame and the lid, the lid has a flat surface to cover the waveguide grooves, and the second circuit board has a probe provided thereon, the probe protruding into the waveguide groove of the sub-casing.

2. (Cancelled)

3. (Original) The waveguide according to Claim 1, wherein the lid has a projected flange formed thereon so as to serve as a fixing surface for a mating waveguide, and the flange has a waveguide through-hole therein so that the waveguide groove is in continuous connection with the waveguide through-hole via an inclined plane formed at an end of the waveguide groove.

4-6. (Cancelled)

- 7. (Previously Presented) The waveguide according to Claim 1, further comprising through-holes provided in the second circuit board, the through-holes having sufficient size to permit bare semiconductor chips to be inserted therein.
- 8. (Previously Presented) The waveguide according to Claim 7, wherein the bare semiconductor chips are bonded to an inner bottom surface of the subcasing through conductive adhesive and are connected to a conductive pattern on the second circuit board through wire bonds.

- 9. (Currently Amended) The waveguide according to Claim 1, further comprising a radiation plate on which the sub-casing is disposed, the radiation plate sized to fit inside the cut-out.
- 10. (Currently Amended) The waveguide according to Claim 9, further comprising an adhesive radiation sheet interposed between the sub-casing and the radiation plate, <u>and the adhesive</u> radiation sheet smoothing fine irregularities on a contact surface between the sub-casing and the radiation plate.
- 11. (Currently Amended) The waveguide according to Claim 1, wherein the main casing has an opening whose-with an end that defines the cut-out, the subcasing has a protrusion-is disposed in the opening such that the sub-casing protrusion-does not contact the main casing within the opening.
- 12. (Currently Amended) The waveguide according to Claim 9, wherein the main casing has an opening with an whose end that defines the cut-out, the sub-casingradiation plate has a protrusion disposed in the opening such that the protrusion does not contact the main casing.
- 13. (Previously Presented) The waveguide according to Claim 12, wherein the main casing has alternating depressions and projections formed on both sides of the opening, the projections serve as contact surfaces between the main casing and the radiation plate so as to join the main casing and the radiation plate and the depressions reduce the contact area between the main casing and the radiation plate.

14. (Cancelled)

- 15. (Previously Presented) The waveguide according to Claim 1, wherein the lid has a hole that connects the waveguide grooves in the main and sub-casings with an external element to receive signals propagating through the waveguide grooves and hole.
- 16. (Previously Presented) The waveguide according to Claim 1, wherein the second circuit board is electromagnetically shielded on all sides from the first circuit board.